

U.S.S.N. 10,791,247

Claim Amendments

Please amend claims 1, 3, 13, and 17 as follows:

Please cancel claims 4 and 6 as follows:

Please add new claims 25-26 as follows:

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Listing of Claims

1. (currently amended) A method of cleaning substrates, comprising the steps of:

providing a cleaning fluid;

mixing a solvent with said cleaning fluid to form a non-supercritical cleaning fluid mixture;

delivering said non-supercritical cleaning fluid mixture to a cleaning chamber;

forming a supercritical cleaning fluid from said non-supercritical cleaning fluid mixture in said cleaning chamber; and

contacting the substrate with said supercritical cleaning fluid in said cleaning chamber.

2. (original) The method of claim 1 wherein said cleaning fluid is carbon dioxide.

3. (currently amended) The method of claim 1 wherein said contacting the substrate with said supercritical cleaning fluid

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comprises the step of ~~contacting the substrate with said supercritical cleaning fluid for about 5-10 minutes circulating the supercritical cleaning fluid within said cleaning chamber.~~

Claims 4-6 (cancelled)

7. (original) The method of claim 1 wherein said supercritical cleaning fluid is non-conductive.

8. (original) The method of claim 1 wherein said cleaning fluid is selected from the group consisting of methane, ethane, propane, ammonia, nitric oxide, fluoromethane and difluoromethane.

9. (previously presented) The method of claim 1 wherein said solvent is an alcohol.

10. (original) The method of claim 1 wherein each of said substrates comprises exposed N-doped and P-doped regions.

11. (original) The method of claim 1 wherein each of said substrates comprises an exposed conductive layer.

12. (original) The method of claim 11 wherein each of said

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substrates comprises exposed N-doped and P-doped regions and an exposed conductive layer.

13. (currently amended) A method of cleaning a substrate to reduce galvanic corrosion of a substrate comprising N-doped and P-doped regions and a conductive layer, comprising the steps of:

providing non-supercritical cleaning fluid cleaning solution;

mixing a solvent with said cleaning fluid to form a non-supercritical cleaning fluid mixture;

delivering said non-supercritical cleaning fluid mixture to a cleaning chamber;

forming a supercritical cleaning fluid mixture from said non-supercritical cleaning fluid mixture in said cleaning chamber; and

contacting the substrate with said supercritical cleaning fluid mixture in said cleaning chamber.

14. (cancelled)

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15. (previously presented) The method of claim 13 wherein said non-supercritical cleaning fluid comprises carbon dioxide.

16. (cancelled)

17. (currently amended) A method of cleaning a substrate to reduce galvanic corrosion of exposed conductors, comprising the steps of:

providing said substrate comprising exposed metal lines;

providing a cleaning fluid selected from the group consisting of carbon dioxide, methane, ethane, propane, ammonia, nitric oxide, fluoromethane and difluoromethane;

mixing a solvent with said cleaning fluid to form a non-supercritical cleaning fluid mixture;

delivering said non-supercritical cleaning fluid mixture to a cleaning chamber;

forming a non-conductive supercritical cleaning fluid from said non-supercritical cleaning fluid in said cleaning chamber;

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and

contacting the substrate with said supercritical cleaning fluid.

18. (cancelled)

19. (original) The method of claim 17 wherein said supercritical cleaning fluid is non-conductive.

20. (previously presented) The method of claim 17 wherein said substrate comprises exposed N-doped and P-doped regions.

21. (previously presented) The method of claim 1, wherein the solvent is selected from the group consisting of isopropyl alcohol or other alcohols, ethylene glycol, hydrogen fluoride and ammonium hydroxide.

22. (previously presented) The method of claim 1, wherein the substrate comprises exposed metal lines.

23. (previously presented) The method of claim 13, wherein said non-supercritical cleaning fluid is selected from the group consisting of methane, ethane, propane, ammonia, nitric oxide,

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fluoromethane and difluoromethane.

24. (previously presented) The method of claim 17, wherein said solvent is selected from the group consisting of alcohols, ethylene glycol, hydrogen fluoride and ammonium hydroxide.

25. (new) The method of claim 13 wherein said contacting the substrate with said supercritical cleaning fluid comprises the step of circulating the supercritical cleaning fluid within said cleaning chamber.

26. (new) The method of claim 17 wherein said contacting the substrate with said supercritical cleaning fluid comprises the step of circulating the supercritical cleaning fluid within said cleaning chamber.